

# **MXD8545A**

0.1-3.0GHz SP4T Antenna Tuning Switch

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# **General Description**

The MXD8545A is a CMOS silicon-on-insulator (SOI), single-pole, four-throw (SP4T) switch. The high linearity and ruggedness performance and extremely low insertion loss makes the device an ideal choice for GSM/WCDMA/LTE handset antenna tuning application.

The MXD8545A SP4T switch is provided in a compact QFN 1.1mm x 1.5mm x 0.38mm package. A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

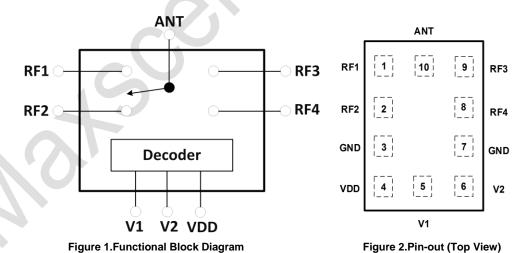
## **Applications**

- GSM/WCDMA/LTE band and mode switching
- Antenna tuning switch

#### **Features**

- Broadband frequency range: 0.1 to 3.0 GHz
- Low insertion 0.50dB @ 2.7 GHz
- High P0.1dB of 43.3dBm
- Positive low voltage control: VC = 1.0 to 3.0 V,
   VDD = 2.5 to 3.3 V, Small QFN (10-pin,
   1.1mm x 1.5mm x 0.38mm) package , MSL1

# **Functional Block Diagram and Pin Function**





# **Application Circuit**

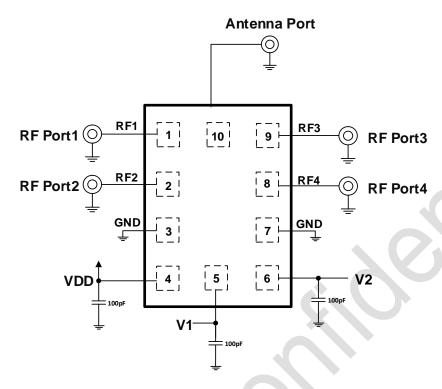


Figure 3. MXD8545A Application Circuit

**Table 1. Pin Description** 

Table 1. Pir	n Descriptio	n			
Pin No.	Name	Description	Pin No.	Name	Description
1	RF1	RF port 1	6	V2	Control Logic #2
2	RF2	RF port 2	7	GND	Ground
3	GND	Ground	8	RF4	RF port 4
4	VDD	DC power supply	9	RF3	RF port 3
5	V1	Control Logic #1	10	ANT	Antenna port

## **Truth Table**

Table 2.

State	V1	V2	RF Path
RF1	0	0	ANT to RF1
RF2	0	1	ANT to RF2
RF3	1	0	ANT to RF3
RF4	1	1	ANT to RF4

**Note:** "1" = 1.0 V to 3.00 V. "0" = 0 V to +0.3 V.

# **Recommended Operation Range**

Table 3.

Parameters	Symbol	Min	Тур	Max	Units
Operation Frequency	f1	0.1	ı	3.0	GHz
Power supply	$V_{DD}$	2.5	2.8	3.3	V
Switch Control Voltage High	$V_{CTL_LH}$	1.0	1.8	3.0	V
Switch Control Voltage Low	$V_{CTL\_L}$	0	0	0.3	V



# **Specifications**

# **Table 4.Electrical Specifications**

B	0	Specification			T (0 III)	
Parameter	Symbol	Min.	Typical	Max.	Units	Test Condition
DC Specifications					•	
Control voltage:						
Low	V <sub>CTL_L</sub>	0	0	0.3	V	
High	V <sub>CTL_H</sub>	1.0	1.8	3.0	V	
Supply voltage	$V_{DD}$	2.5	2.8	3.3	V	V 00V
Supply current	I <sub>DD</sub>		75	110	uA	V <sub>DD</sub> = 2.8 V
Control current	I <sub>CTL</sub>		1	5	uA	V <sub>CTL</sub> = 1.8 V
RF Specifications						
			0.35	0.45	dB	0.8 to 1.0 GHz
Insertion loss	IL		0.45	0.55	dB	1.0 to 2.2 GHz
		26	0.50	0.70	dB dB	2.2 to 3.0 GHz
Isolation	ISO	26 22	28 24		dB dB	0.8 to 1.0 GHz 1.0 to 2.2 GHz
ISOIALIOIT	130	19	22		dB	2.2 to 3.0 GHz
Return loss	S <sub>11</sub>	13	20		dB	0.8 to 3.0 GHz
Voltage Standing						
Wave Ratio	VSWR		1.20			0.8 to 3.0 GHz
On Resistance (RF1/2/3/4 to ANT)	Ron		1.05	1.15	Ω	Switch on Path
OFF Capacitance (RF1/2/3/4 to ANT)	Coff		130	150	fF	Switch off Path
Input 0.1 dB compression point	P <sub>0.1dB</sub>	+43	+43.3		dBm	0.8 to 3.0 GHz, ANT to RF1/2/3/4
Peak RF operating voltage	$V_{peak}$		45		V	f0 = 700 to 2700 MHz, 25% duty cycle
LTE TX harmonic	2f0		-80	-70	dBm	f0 = 700 to 2700 MHz, PIN = +26
(RF1/2/3/4 to ANT)	3f0		-90	-80	dBm	dBm
GSM LB harmonic	2f0		-60	-50	dBm	f0 = 824  to  915  MHz, PIN = +35
(RF1/2/3/4 to ANT)	3f0		-60	-50	dBm	dBm
GSM HB harmonic	2f0		-60	-50	dBm	f0 = 1710  to  2690  MHz,  PIN = +33
(RF1/2/3/4 to ANT)	3f0		-60	-50	dBm	dBm
Second order intermodulation	IMD2		-112	-105	dBm	CW Carrier on RF Port, +20 dBm CW Interferer on ANT port, -15 dBm
Third order intermodulation	IMD3		-112	-105	dBm	CW Carrier on RF Port, +20 dBm CW Interferer on ANT port, -15 dBm
Switching on time			3.0	5.0	μs	50% VCTL to 90% RF
Switching off time			3.0	5.0	μs	50% VCTL to 10% RF
Startup time			10	20	μs	Power off state to any RF switch state



#### **Table 5. IMD2 Test Conditions**

Band	In-band freq	CW C	arrier	CW Interferer	
Dallu	MHz	MHz	dBm	MHz	dBm
1 Low	2140	1950	+20	190	-15
1 High	2140	1950	+20	4090	-15
5 Low	881.5	836.5	+20	45	-15
5 High	881.5	836.5	+20	1718	-15

#### **Table 6. IMD3 Test Conditions**

Band	In-band freq	CW C	arrier	CW Interferer	
Ballu	MHz	MHz	dBm	MHz	dBm
1	2140	1950	+20	1760	-15
5	881.5	836.5	+20	791.5	-15

# **Absolute Maximum Ratings**

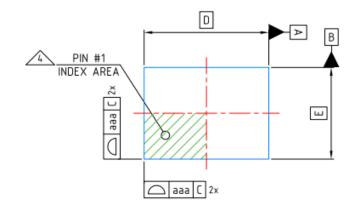
## **Table 7. Maximum ratings**

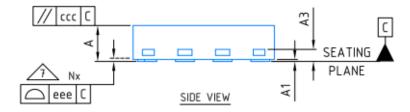
Parameters	Symbol	Minimum	Maximum	Units
Supply voltage	$V_{DD}$	+2.5	+3.6	V
Digital control voltage	$V_{CTL}$	0	+3.6	V
input power (RF port, 25% DC)	P <sub>IN</sub>		+43.8	dBm
input power (RF port, VSWR =10:1, CW)	P <sub>IN</sub>		+38	dBm
input power ( RF port, LTE 10M Full RB, VSWR =10:1,CW)	P <sub>IN</sub>		+32	dBm
input power (GSM LB, CW and 50% DC)	P <sub>IN</sub>		+40	dBm
input power ( GSM HB, CW and 50% DC )	P <sub>IN</sub>	>	+38	dBm
Operating temperature	T <sub>OP</sub>	-35	+90	°C
Storage temperature	T <sub>STG</sub>	<b>–</b> 55	+150	°C
Electrostatic Discharge Human body model (HBM), Class 2	ESD_HBM		1500	
Machine Model (MM), Class B	ESD_MM		150	V
Charged device model (CDM), Class III			500	

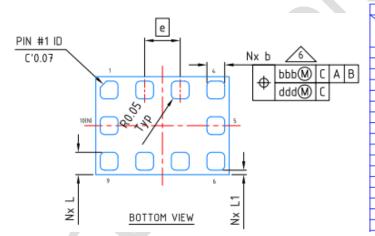
**Note:** Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.



# **Package Outline Dimension**







Dimension Table					
X2					
MINIMUM	NOMINAL	MAXIMUM			
0.31	0.38	0.40			
0.00	0.02	0.05			
	0.12 Ref.				
0.15	0.20	0.25			
1.50 BSC					
1.10 BSC					
	0.40 BSC				
0.15	0.25	0.35			
	0.05				
	0.05				
	0.07				
	0.10				
	0.05				
0.08					
10					
4					
	1				
	MINIMUM 0.31 0.00  0.15	MINIMUM NOMINAL 0.31 0.38 0.00 0.02 0.12 Ref. 0.15 0.20 1.50 BSC 1.10 BSC 0.40 BSC 0.15 0.25 0.05 0.07 0.10 0.05 0.08 10			

Figure 4. Package outline dimension



#### **Reflow Chart**

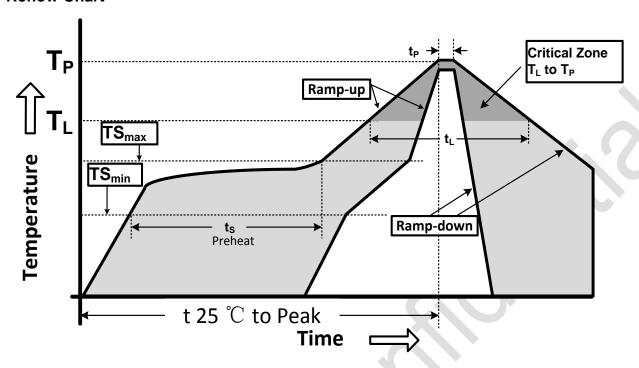


Figure 5. Recommended Lead-Free Reflow Profile

#### Table 8.

Profile Parameter	Lead-Free Assembly, Convection, IR/Convection
Ramp-up rate (TS <sub>max</sub> to T <sub>p</sub> )	3℃/second max.
Preheat temperature (TS <sub>min</sub> to TS <sub>max</sub> )	150℃ to 200℃
Preheat time (t <sub>s</sub> )	60 - 180 seconds
Time above TL , 217 $^{\circ}$ C $(t_L)$	60 - 150 seconds
Peak temperature (T <sub>p</sub> )	260℃
Time within 5°C of peak temperature(t <sub>p</sub> )	20 - 40 seconds
Ramp-down rate	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

## **ESD Sensitivity**

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

## **RoHS Compliant**

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

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